

 CENTER CONTACT
 GROUND CONTACT


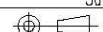
RECOMMENDED PCB LAYOUT
 (TOLERANCE:±0.05)

NOTE:

1. MATERIAL:
 - 1.1.HOUSING: THERMOPLASTIC,UL94V-0, COLOR:BLACK.
 - 1.2.CENTER CONTACT : PHOSPHOR BRONZE.
 - 1.3.GROUND CONTACT: PHOSPHOR BRONZE.
2. FINISH:
 - 2.1.CENTER CONTACT 3u" ON CONTACT AREA, GOLD FLASH OTHER AREA; 50u' MIN. NICKEL UNDERPLATING.
 - 2.2.GROUND CONTACT 1u" MIN GOLD PLATING; OR 100u" MIN SILVER PLATING; OR 100u" MIN TIN PLATING; 50u' MIN. NICKEL UNDERPLATING OVERALL.
3. PART NUMBER DESCRIPTION:

PART NO.	DESCRIPTION
MRFR3-2000400	GROUND CONTACT GOLD PLATING;
MRFR3-2100400	GROUND CONTACT SILVER PLATING;
MRFR3-2200400	GROUND CONTACT TIN PLATING;

4. APPLIED TO IR SOLDERING PROCESS
5. COPLANARITY: 0.10mm MAX.

UNLESS OTHERWISE SPECIFIED TOLERANCE X ± 0.30/012 X' ± 1" XX ± 0.20/008 X" ± XXX ± 0.10/004 XX' ±		 www.allconnectors.de Tel.: 0049 711 7098503 70794 Filderstadt, Germany	
SCALE:	UNIT: mm/inch	info@allconnectors.de Fax: 0049 711 7098504 Kettnerstr. 25	
DRAWN: JASON	97/05/25	DRAWN NAME: CRF-101-007	
CHECKED: David	97/05/26	TITLE: MRF III RECEPTACLE	
APPROVED Sunny-BH	97/05/27		
	SIZE	REV. 0	

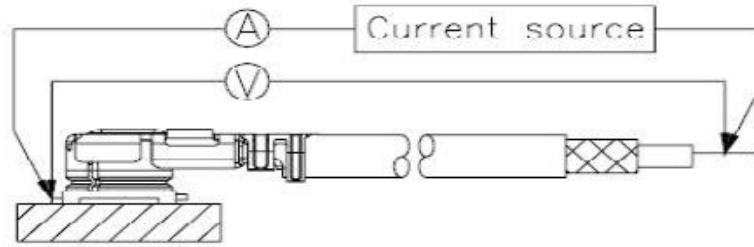


Fig.3 Contact Resistance

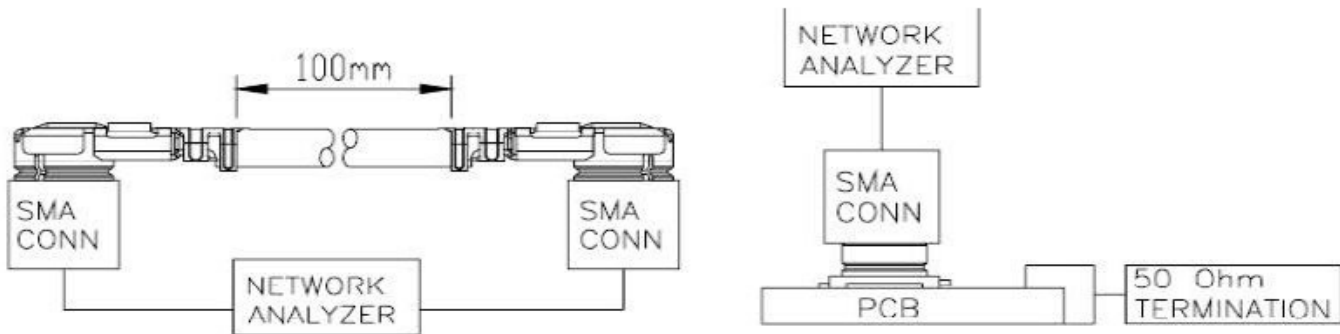


Fig.4 VSWR AND INSERTION LOSS

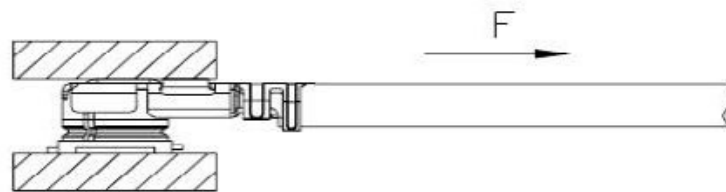


Fig.5 Crimp strength

NOTE : The Above Picture Are The MRF II Products That do Reference.

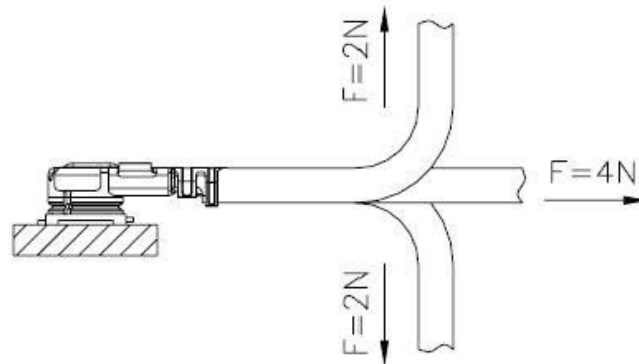


Fig.6 Cable retention force

NOTE : The Above Picture Are The MRF II Products That do Reference.

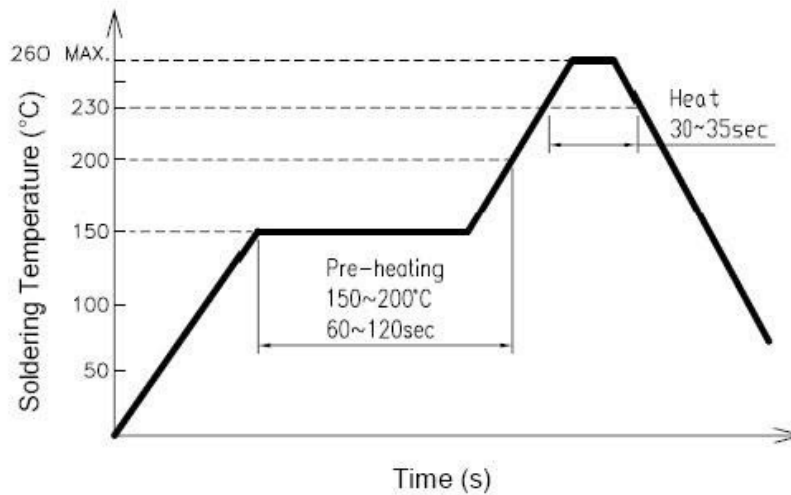


Fig.7 RECEPTACLE Temperature Profile of Reflow Soldering